

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2396	"156"/\$.ccls. and (control\$5) and (stretch)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L2	2	"156"/\$.ccls. and ((correct or correcting or correction) near2 (value or figure or amount)) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (pcb or (circuit near2 board))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L3	409	(156/358).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L4	441	(156/351).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L5	502	(156/359).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L6	269	(156/360).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L7	775	(156/378).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:58
L8	221	(156/379).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15

L9	120	(100/46).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L10	234	(100/47).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L11	352	(100/48).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L12	316	(100/50).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L13	94	(100/51).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L14	333	(438/7).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L15	970	(438/16).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L16	157	"156"/\$.ccls. and (control\$5) and (stretch) and (semiconductor or IC or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L17	40	"156"/\$.ccls. and (control\$5) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (semiconductor or IC or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15

L18	40	"156"/\$.ccls. and (control\$5) and (stretch) and (pcb or (circuit near2 board))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L19	8	"156"/\$.ccls. and (control\$5) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (pcb or (circuit near2 board))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:21
L20	83	"156"/\$.ccls. and ((heating or heater or weld or welding or bond or bonding) near2 head) and control and (stretch or deviation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/28 14:15
L21	1340	(156/64).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L22	19	"156"/\$.ccls. and (control\$5) and (flexure) and (pcb or (circuit near2 board))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:15
L23	77	"156"/\$.ccls. and (control\$5) and (flexure) and (semiconductor or IC or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:21
L24	7109268	JP 11-54877	JPO	OR	OFF	2004/11/28 14:15
L25	0	11-54877	JPO	OR	OFF	2004/11/28 14:15
L26	0	11-054877	JPO	OR	OFF	2004/11/28 14:15
L27	0	h11-054877	JPO	OR	OFF	2004/11/28 14:15
L28	0	"054877"	JPO	OR	OFF	2004/11/28 14:15
L29	1	"11054877"	JPO	OR	OFF	2004/11/28 14:15
L30	3	((("5858806") or ("5243735") or ("6458236"))).PN.	USPAT; USOCR	OR	OFF	2004/11/28 14:15
L31	1	("5243755").PN.	USPAT; USOCR	OR	OFF	2004/11/28 14:15
L32	3	((("5858806") or ("5243755") or ("6458236"))).PN.	USPAT; USOCR	OR	OFF	2004/11/28 14:15
L33	91	(display near3 panel) and ((heating or heater or weld or welding or bond or bonding) near2 head) and control and (stretch or deviation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/28 14:15

L34	16	(display near3 board) and ((heating or heater or weld or welding or bond or bonding) near2 head) and control and (stretch or deviation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/28 14:15
L35	112	(control\$5) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (pcb or (circuit near2 board)) and (bond or bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:56
L36	191	(control\$5) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (pcb or (circuit near2 board)) and (bond or bonding)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/28 14:21
L37	2179	(bond or bonding or solder) and (control\$5) and (flexure) and (semiconductor or IC or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:34
L38	75	thermocompression and (control\$5) and (flexure) and (semiconductor or IC or wafer or chip)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:34
L39	5	(control\$5) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (pcb or (circuit near2 board)) and (thermocompression)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:56
L40	5	(control\$5) and (load near2 (deviation or modification or aberration or aberation or change or adjustment)) and (pcb or (circuit near2 board)) and (thermocompression)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/28 14:58
L41	271	(29/877).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/11/28 14:58
L42	3	41 and (thermocompression)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/11/28 14:58